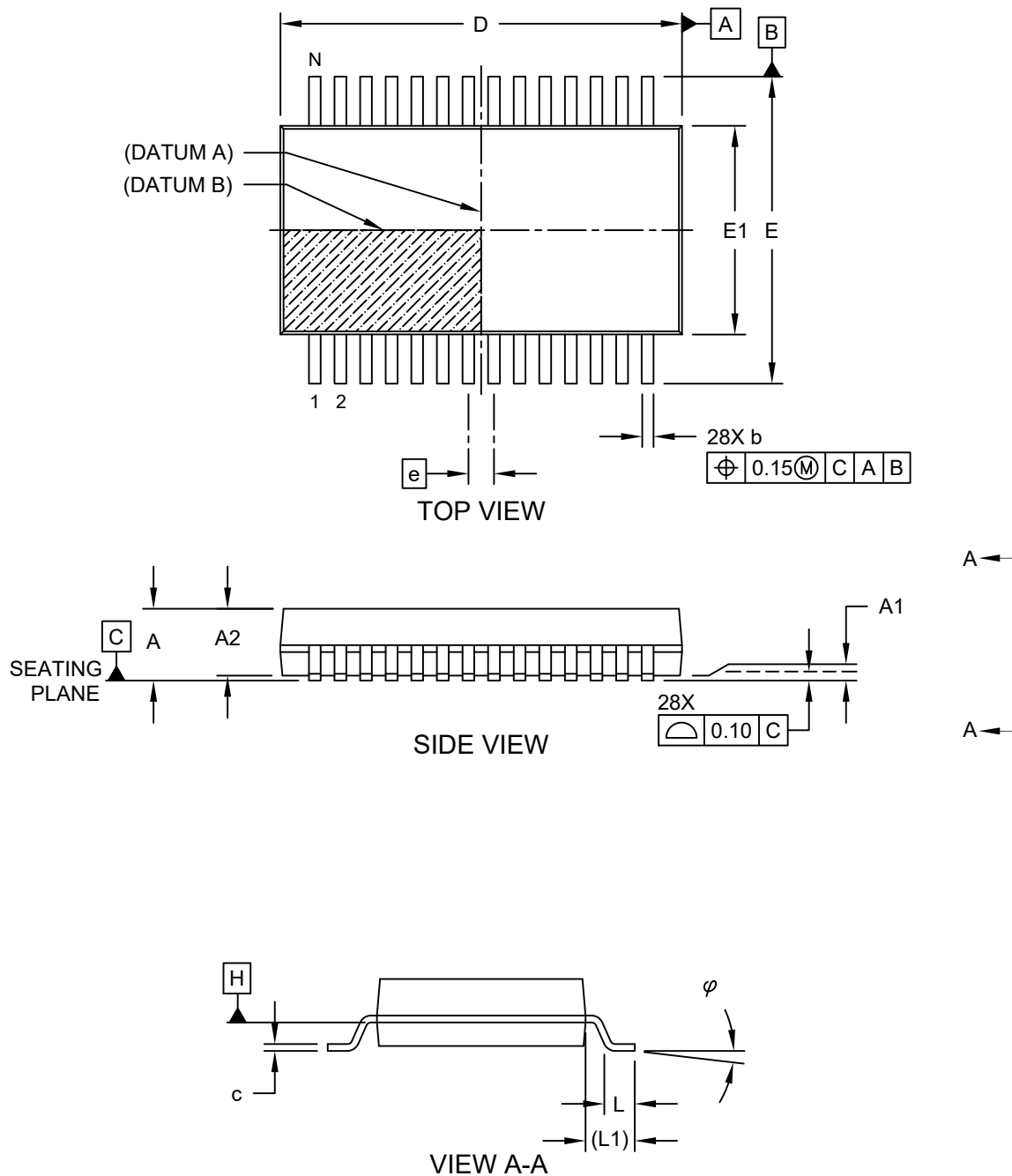


Packaging Diagrams and Parameters

28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

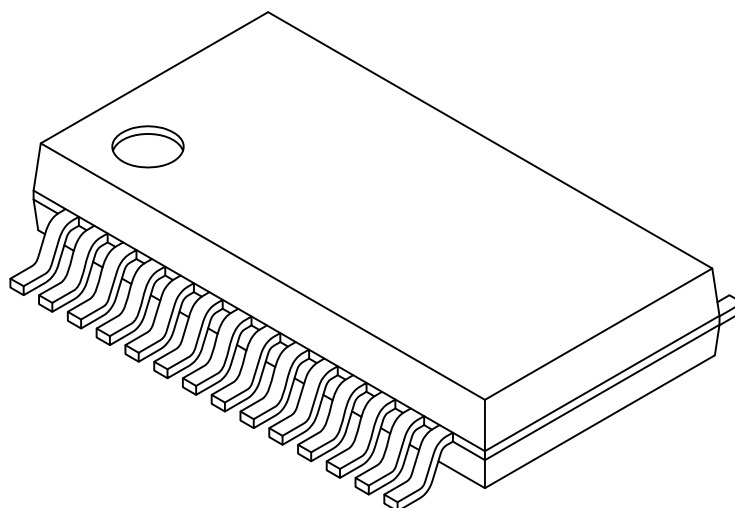
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Packaging Diagrams and Parameters

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Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	0.65 BSC		
Overall Height	A	-	-	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	-	-
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1	1.25 REF		
Lead Thickness	c	0.09	-	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	-	0.38

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20mm per side.
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

